



SOT788-2

plastic, thermal enhanced very thin quad flat package; no leads; 28 terminals; 6 x 6 x 0.85 mm body

1 August 2016

Package information

1. Package summary

Dimensions (mm)	6 x 6 x 0.85
Terminal position code	B (bottom)
Package type descriptive code	HVQFN28
Package outline version code	SOT788-2
Manufacturer package code	SOT788
Package type industry code	HVQFN
Package outline version description	plastic, thermal enhanced very thin quad flat package; no leads; 28 terminals; 6 x 6 x 0.85 mm body
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P
Mounting method type	S (surface mount)
Package life cycle status	REL
Security status	COMPANY PUBLIC
Issue date	21-7-2016
Customer specific indicator	N
Maturity	Product

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A	seated height	-	-	-	1	mm
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
e	nominal pitch	-	-	0.65	-	mm



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2. Package outline

HVQFN28: plastic, thermal enhanced very thin quad flat package; no leads; 28 terminals; 6 x 6 x 0.85 mm body

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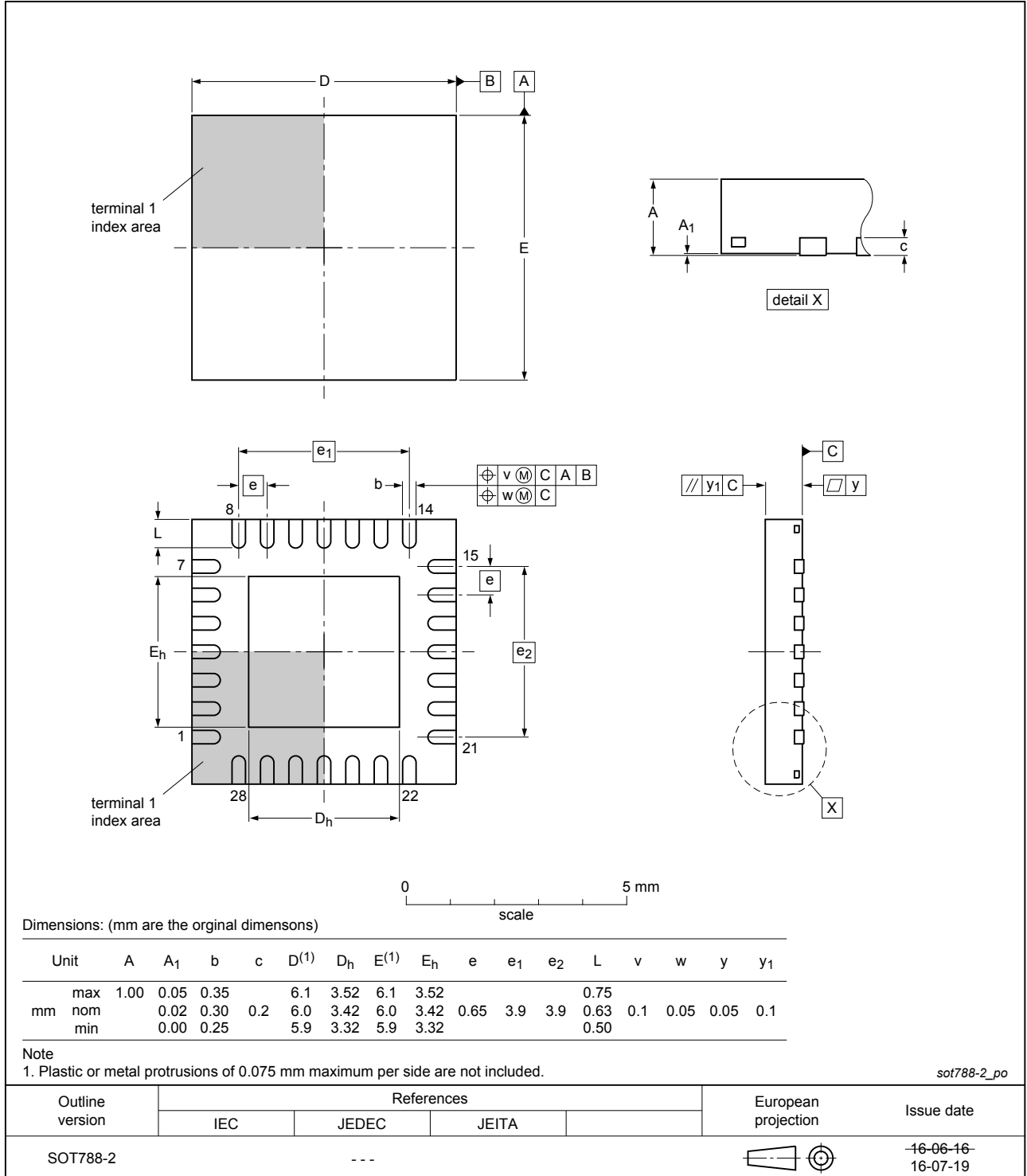


Fig. 1. Package outline HVQFN (SOT788-2)

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3. Legal information

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